



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2019-02-14
Contact Name *	Refer to Supplier Comment section	Refer to Supplier Comment section	
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
LMV339IDT	CDK7*V339AAL	A	BO2A	2019-02-14
Amount	UoM	Unit type	ST ECOPACK Grade	
130.00	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
DSO	8.6x3.9x1.52	14	gull wing
Comment	Package: K7 SO 14 .15 TO JEDEC MS-012		

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-15th Jan 2019				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	CDK7*V339AAL					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.947	mg	supplier	die	Silicon (Si)	7440-21-3		0.916	mg	967265	7046
				supplier	metallization	Aluminium (Al)	7429-90-5		0.008	mg	8448	62
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	1056	8
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	1056	8
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	2112	15
				supplier	Passivation	Silicon Oxide	7631-86-9		0.019	mg	20063	146
Leadframe	Copper & its alloys	38.384	mg	supplier	alloy	Copper (Cu)	7440-50-8		35.266	mg	918768	271277
				supplier	alloy	Iron (Fe)	7439-89-6		0.829	mg	21598	6377
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.050	mg	1303	385
				supplier	alloy	Zinc (Zn)	7440-66-6		0.043	mg	1120	331
				supplier	metallization	Nickel (Ni)	7440-02-0		0.460	mg	11984	3538
				supplier	metallization	Palladium (Pd)	7440-05-3		0.029	mg	756	223
				supplier	metallization	Gold (Au)	7440-57-5		0.012	mg	313	92
				supplier	metallization	Silver (Ag)	7440-22-4		1.695	mg	44159	13038
				supplier	metallization	Silver (Ag)	7440-22-4		0.339	mg	904000	2608
Die attach	Other inorganic materials	0.375	mg	supplier	glue	Silver (Ag)	7440-22-4		0.339	mg	904000	2608
				supplier	glue	acrylate	Proprietary		0.019	mg	50667	146
				supplier	glue	Methacrylate	Proprietary		0.015	mg	40000	115
				supplier	glue	acrylate	Proprietary		0.001	mg	2667	8
				SVHC	glue	NMP	872-50-4		0.001	mg	2667	8
Encapsulation	Other Organic Materials	89.267	mg	supplier	wire	Copper (Cu)	7440-50-8		0.127	mg	1000000	977
				supplier	mold compound	Silica, vitreous	60676-86-0		77.306	mg	866009	594662
				supplier	mold compound	Epoxy Resin	Proprietary		6.695	mg	75000	51500
				supplier	mold compound	Phenol Resin	Proprietary		4.463	mg	49996	34331
				supplier	mold compound	Carbon black	1333-86-4		0.446	mg	4996	3431
connections coating	Solder	0.900	mg	supplier	mold compound	Bismuth (Bi)	7440-69-9		0.357	mg	3999	2746
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.900	mg	1000000	6923